

September 1983 Revised February 1999

# MM74HC259 8-Bit Addressable Latch/3-to-8 Line Decoder

### **General Description**

The MM74HC259 device utilizes advanced silicon-gate CMOS technology to implement an 8-bit addressable latch, designed for general purpose storage applications in digital systems.

The MM74HC259 has a single data input (D), 8 latch outputs (Q1–Q8), 3 address inputs (A, B, and C), a common enable input (G), and a common CLEAR input. To operate this device as an addressable latch, data is held on the D input, and the address of the latch into which the data is to be entered is held on the A, B, and C inputs. When ENABLE is taken LOW the data flows through to the addressed output. The data is stored when ENABLE transitions from LOW-to-HIGH. All unaddressed latches will remain unaffected. With enable in the HIGH state the device is deselected, and all latches remain in their previous state, unaffected by changes on the data or address

inputs. To eliminate the possibility of entering erroneous data into the latches, the enable should be held HIGH (inactive) while the address lines are changing.

If enable is held HIGH and CLEAR is taken LOW all eight latches are cleared to a LOW state. If enable is LOW all latches except the addressed latch will be cleared. The addressed latch will instead follow the D input, effectively implementing a 3-to-8 line decoder.

All inputs are protected from damage due to static discharge by diodes to  $\rm V_{CC}$  and ground.

### **Features**

- Typical propagation delay: 18 ns
- Wide supply range: 2-6V
- Low input current: 1 µA maximum
- Low quiescent current: 80 µA maximum (74HC Series)

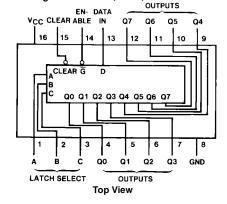
### **Ordering Code:**

Order Number	Package Number	Package Description
MM74HC259M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow
MM74HC259SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC259MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC259N	N16F	16-Lead Plastic Dual-In-Line Package (PDIP) JEDEC MS-001_0_300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Connection Diagram

Pin Assignments for DIP, SOIC, SOP and TSSOP



### **Latch Selection Table**

Se	elect Inpu	its	Latch
С	В	Α	Addressed
L	L	L	0
L	L	Н	1
L	Н	L	2
L	Н	Н	3
Н	L	L	4
Н	L	Н	5
Н	Н	L	6
Н	Н	Н	7

H = HIGH level, L = LOW level

D = the level at the data input

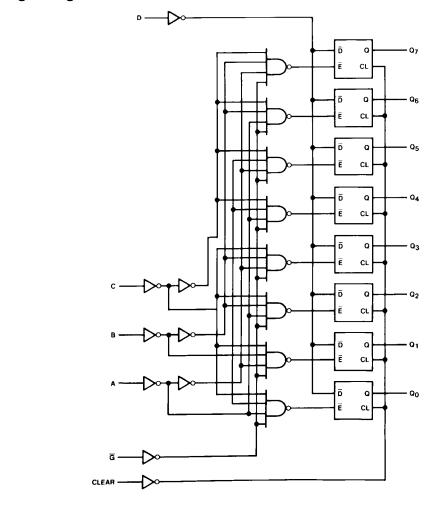
 $Q_{i0}$  the level of  $Q_i$  (i = 0, 1 . . . 7, as appropriate) before the indicated steady-state input

conditions were established.

## **Truth Table**

Inputs		Outputs of	Each	
		Addressed	Other	Function
Clear G		Latch	Output	
Н	L	D	Q <sub>i0</sub>	Addressable Latch
Н	Н	$Q_{i0}$	Q <sub>i0</sub>	Memory
L	L	D	L	8-Line Decoder
L	Н	L	L	Clear

# Logic Diagram



### **Absolute Maximum Ratings**(Note 1)

(Note 2)

Lead Temperature (T<sub>L</sub>)

(Soldering 10 seconds)

Supply Voltage (V <sub>CC</sub> )	-0.5 to +7.0V
DC Input Voltage (V <sub>IN</sub> )	$-1.5$ to $V_{CC}+1.5V$
DC Output Voltage (V <sub>OUT</sub> )	$-0.5$ to $V_{CC} + 0.5 V$
Clamp Diode Current (I <sub>IK</sub> , I <sub>OK</sub> )	±20 mA
DC Output Current, per pin (I <sub>OUT</sub> )	±25 mA
DC $V_{CC}$ or GND Current, per pin ( $I_{CC}$ )	±50 mA
Storage Temperature Range (T <sub>STG</sub> )	-65°C to +150°C
Power Dissipation (P <sub>D</sub> )	
(Note 3)	600 mW
S.O. Package only	500 mW

# Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )	2	6	V
DC Input or Output Voltage	0	$V_{CC}$	V
$(V_{IN}, V_{OUT})$			
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns
Note 1: Absolute Maximum Ratings are those	values b	eyond whi	ch dam-

age to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: – 12 mW/°C from 65°C to 85°C

### DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
			VCC	Тур		Guaranteed Li	mits	Units
V <sub>IH</sub>	Minimum HIGH Level		2.0V		1.5	1.5	1.5	V
	Input Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V <sub>IL</sub>	Maximum LOW Level		2.0V		0.5	0.5	0.5	V
	Input Voltage		4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V <sub>OH</sub>	Minimum HIGH Level	$V_{IN} = V_{IH}$ or $V_{IL}$						
	Output Voltage	$ I_{OUT}  \le 20 \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or $V_{IL}$						
		$ I_{OUT}  \le 4.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	V
		$ I_{OUT}  \le 5.2 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	V
V <sub>OL</sub>	Maximum LOW Level	$V_{IN} = V_{IH}$ or $V_{IL}$						
	Output Voltage	$ I_{OUT}  \le 20 \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or $V_{IL}$						
		$ I_{OUT}  \le 4.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V
		$ I_{OUT}  \le 5.2 \text{ mA}$	6.0V	0.2	0.26	0.33	0.4	V
I <sub>IN</sub>	Maximum Input	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μΑ
	Current							
I <sub>CC</sub>	Maximum Quiescent	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0V		8.0	80	160	μΑ
	Supply Current	$I_{OUT} = 0 \mu A$						

Note 4: For a power supply of 5V ±10% the worst case output voltages (V<sub>OH</sub>, and V<sub>OL</sub>) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub>=5.5V and 4.5V respectively. (The V<sub>IH</sub> value at 5.5V is 3.85V.) The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and I<sub>O2</sub>) occur for CMOS at the higher voltage and so the 6.0V values should be used.

### **AC Electrical Characteristics**

(V<sub>CC</sub> = 5.0V, T<sub>A</sub> = 25°C, t<sub>f</sub> = t<sub>f</sub> = 6 ns, C<sub>L</sub> = 15 pF unless otherwise specified.)

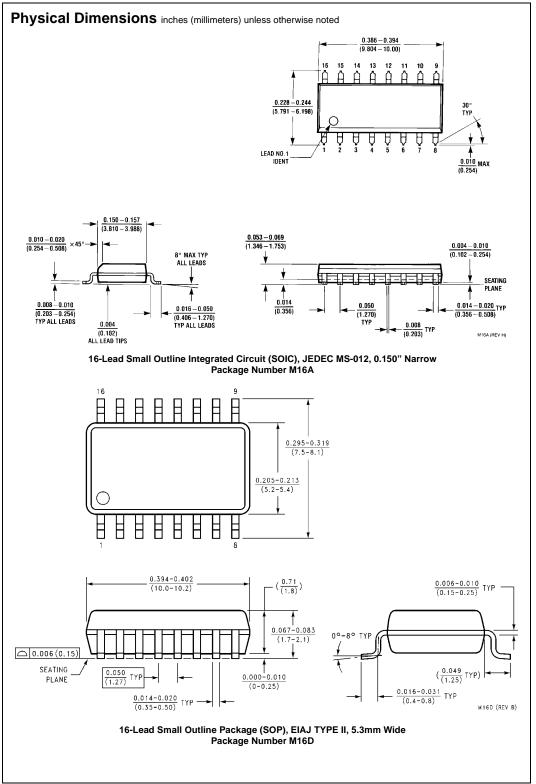
Symbol	Parameter	Conditions	Тур	Guaranteed	Units
	T di dillotoi	Conditions	.,,,,	Limit	00
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay		18	32	ns
	Data to Output				
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay		20	38	ns
	Select to Output				
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay		20	35	ns
	Enable to Output				
t <sub>PHL</sub>	Maximum Propagation Delay		17	27	ns
	Clear to Output				
t <sub>W</sub>	Minimum Enable Pulse Width		10	16	ns
t <sub>W</sub>	Minimum Clear Pulse Width		10	16	ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Time			500	ns
t <sub>s</sub>	Minimum Setup Time Select or		15	20	ns
	Data to Enable				
t <sub>H</sub>	Minimum Hold Time Data or		-2	0	ns
	Address to Enable				

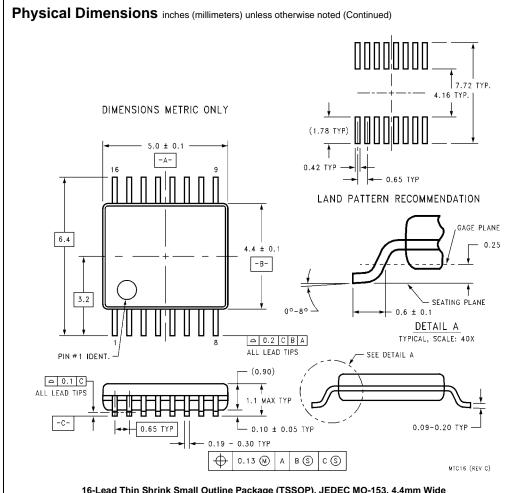
### **AC Electrical Characteristics**

 $t_r = t_f = 6 \text{ ns}, \ C_L = 50 \text{ pF}, \ V_{CC} = 2.0 \text{V} - 6.0 \text{V}$ 

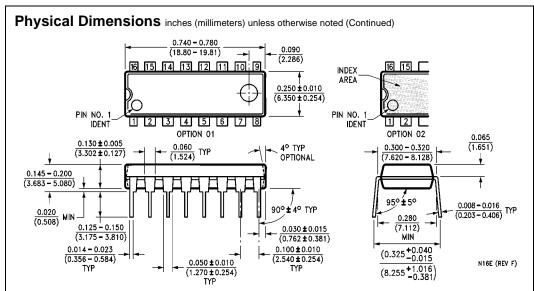
Symbol	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> =	25°C	$T_A = -40$ to $85^{\circ}C$	T <sub>A</sub> = -55 to 125°C	Units
3,501	i didiliotoi	Conditions	-,,,	Тур		Guaranteed Limits		
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay		2.0V	60	180	225	250	ns
	Data to Output		4.5V	19	37	46	52	ns
			6.0V	17	32	40	45	ns
$t_{PHL}, t_{PLH}$	Maximum Propagation Delay		2.0V	72	220	275	310	ns
	Select to Output		4.5V	21	43	54	60	ns
			6.0V	18	37	46	52	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay		2.0V	65	200	250	280	ns
	Enable to Output		4.5V	27	40	50	58	ns
			6.0V	23	35	44	50	ns
t <sub>PHL</sub>	Maximum Propagation Delay		2.0V	50	150	190	210	ns
	Clear to Output		4.5V	18	31	39	44	ns
			6.0V	16	26	32	37	ns
t <sub>W</sub>	Minimum Pulse Width		2.0V		80	100	120	ns
	Clear or Enable		4.5V		16	20	24	ns
			6.0V		14	18	20	ns
t <sub>s</sub>	Minimum Setup Time Address		2.0V		100	125	150	ns
	or Data to Enable		4.5V		20	25	28	ns
			6.0V		15	19	25	ns
t <sub>H</sub>	Minimum Hold Time Address		2.0V	-10	0	0	0	ns
	or Data to Enable		4.5V	-2	0	0	0	ns
			6.0V	-2	0	0	0	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Rise		2.0V	30	75	95	110	ns
	and Fall Time		4.5V	8	15	19	22	ns
			6.0V	7	13	16	19	ns
C <sub>IN</sub>	Input Capacitance			5	10	10	10	pF
C <sub>PD</sub>	Power Dissipation	(per package)		80				pF
	Capacitance (Note 5)							

Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PDS} \ V_{CC} \ f + I_{CC}$ .





16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC16



16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N16E

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